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Title of Change:	MT9V124 Datasheet Update
Effective date:	23 May 2018
Contact information:	Contact your local ON Semiconductor Sales Office or <Sonya.Yip@onsemi.com>
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☒ Other Documentation
Change Sub-Category(s):	☐ Manufacturing Site Change/Addition ☐ Material Change ☒ Datasheet/Product Doc change ☐ Manufacturing Process Change ☐ Product specific change ☐ Shipping/Packaging/Marking ☐ Other: _____
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: None

Description and Purpose:

MT9V124 Datasheet was updated to correct documentation errors. These changes do not affect form, fit, or function of the product.

MT9V124 Datasheet Changes

1. **Updated Output Interface section**
   a. Removed reference to MIPI
   b. Changed 8-bit parallel port to LVDS serial interface
   c. Product only has LVDS serial interface

   Old Output Interface Section:

   Output Interface
   The output interface block can select either raw data or processed data. Image data is provided to the host system by an 8-bit parallel port (up to 22 Mb/sec) or by a serial MIPI port (264 MHz LVDS clock with 8-bit and 10-bit support). The parallel output port provides 8-bit YCbCr, YUV, 565 RGB, BT656, processed Bayer data or extended 10-bit Bayer data achieved using 8 + 2 format.

   New Output Interface Section:

   Output Interface
   The output interface block can select either raw data or processed data. Image data is provided to the host system by an LVDS serial interface. The LVDS output port provides 8-bit YCbCr, YUV, 565 RGB, BT656, processed Bayer data or extended 10-bit Bayer data achieved using 8 + 2 format.

2. Remove Table 19

   a. Dimensions in table 19 correspond to the old package drawing format

   b. Package dimensions are now located in the ON Semi formatted CASE 570BN ISSUE A (package drawing)
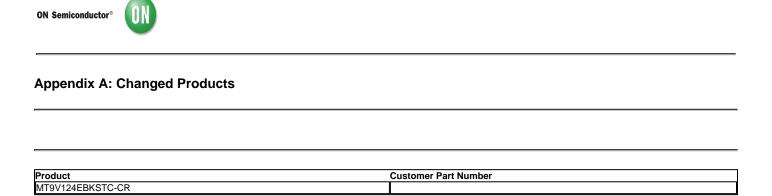
<u>Old Table 19:</u>

Table 19. PACKAGE DIMENSION

Parameter	Symbol	Nominal	Min	Max	Nominal	Min	Max
		Millimeters			Inches		
Package Body Dimension X	A	2.69355	2.66855	2.71855	0.10605	0.10506	0.10703
Package Body Dimension Y	B	2.69355	2.66855	2.71855	0.10605	0.10506	0.10703
Package Height	C	0.670	0.615	0.725	0.02638	0.02421	0.02854
Cavity Height (Glass to Pixel Distance)	C4	0.041	0.037	0.045	0.00161	0.00146	0.00177
Glass Thickness	C3	0.400	0.390	0.410	0.01575	0.01535	0.01614
Package Body Thickness	C2	0.570	0.535	0.605	0.02244	0.02106	0.02382
Ball Height	C1	0.100	0.070	0.130	0.00394	0.00276	0.00512
Ball Diameter	D	0.200	0.170	0.230	0.00787	0.00669	0.00906
Total Ball Count	N	25					
Ball Count X Axis	N1	5					
Ball Count Y Axis	N2	5					
UBM	U	0.240	0.230	0.250	0.00945	0.00906	0.00984
Pins Pitch X Axis	J1	0.500	0.490	0.510	0.01969	0.01929	0.02008
Pins Pitch Y Axis	J2	0.500	0.490	0.510	0.01969	0.01929	0.02008
BGA Ball Center to Package Center Offset in X-direction	X	0	−0.025	0.025	0	−0.00098	0.00098
BGA Ball Center to Package Center Offset in Y-direction	Y	0	−0.025	0.025	0	−0.00098	0.00098
Edge to Ball Center Distance Along X Axis	S1	0.347	0.317	0.377	0.01365	0.01247	0.01483
Edge Ball Center Distance Along Y Axis	S2	0.347	0.317	0.377	0.01365	0.01247	0.01483

List of Affected Standard Parts:

MT9V124D00STCK22DC1-200

MT9V124EBKSTC-CR

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Appendix A: Changed Products

Product	Customer Part Number
MT9V124EBKSTC-CR	